DECLARED MATERIAL LIST		ORIGINATOR : LAM	
SPACECRAFT :	HERSCHEL	DOC. NUMBER :	LAM/ELE/FTS/011008.01
SYSTEM / EXPERIMENT :	SPIRE	SHEET No :	1 /
SUB SYSTEM :	FTS	ISSUE :	0 . 0
		DATE :	08 – 10 - 2001

Material list	Component ID	Name and type of product	Specification	Size	Processing parameters	Outgassing	Ok to bake at 80°C ?	Thermal and vacuum stable ?	OK at 4°K ?	Manufacturer	Remarks, approval reference
1	Bonding for optoelectronic components in the encoder head	EPO-TEK H20E		< 1 g		TWL 1.18% VCM 0.01%	Y			Epoxy Technology Inc	
2	Electronic PCB located in the WE (MAC, SMEC, BSM, backplane)	FR4		TBD		TBD	Y		N/A	TBD	
3	Electronic PCBs located in the mechanism (encoder head, preamplifier, connection board)	FR4		TBD		TBD	Y		TBD	TBD	
4	Electronic flex-rigid PCB located in the mechanism (encoder head)	Kapton		TBD		TBD	Y		TBD	TBD	